

# **GenX3™ 1200V** IGBT w/ Diode

## **IXGR55N120A3H1**

1200V 30A ≤ 2.35V

(Electrically Isolated Tab)

Ultra-Low-Vsat PT IGBTs for up to 3kHz Switching



| ISOPLUS 247™ |              |
|--------------|--------------|
|              |              |
|              |              |
| G C E        | Isolated Tab |

| G = Gate    | C = Collector |
|-------------|---------------|
| E = Emitter |               |

| Symbol            | Test Conditions   | Maximum Ratings          |       |  |
|-------------------|---|--------------------------|-------|--|
| V <sub>CES</sub>  | T <sub>J</sub> = 25°C to 150°C  | 1200                     | V     |  |
| V <sub>CGR</sub>  | $T_{_{\mathrm{J}}}$ = 25°C to 150°C, $R_{_{\mathrm{GE}}}$ = 1M $\Omega$ | 1200                     | V     |  |
| V <sub>GES</sub>  | Continuous  | ±20                      | V     |  |
| V <sub>GEM</sub>  | Transient   | ±30                      | V     |  |
| I <sub>C25</sub>  | T <sub>C</sub> = 25°C ( Chip Capability )                               | 70                       | A     |  |
| I <sub>C110</sub> | $T_{c} = 110^{\circ}C$  | 30                       | Α     |  |
| I <sub>F110</sub> | $T_{c} = 110^{\circ}C$  | 44                       | Α     |  |
| I <sub>CM</sub>   | $T_{\rm c}$ = 25°C, 1ms   | 330                      | Α     |  |
| SSOA              | $V_{GF} = 15V, T_{VJ} = 125^{\circ}C, R_{G} = 3\Omega$                  | I <sub>CM</sub> = 110    | A     |  |
| (RBSOA)           | Clamped Inductive Load  | @ 0.8 • V <sub>CES</sub> |       |  |
| P <sub>c</sub>    | T <sub>C</sub> = 25°C   | 200                      | W     |  |
| T <sub>J</sub>    |   | -55 +150                 | °C    |  |
| $\mathbf{T}_{JM}$ |   | 150                      | °C    |  |
| T <sub>stg</sub>  |   | -55 +150                 | °C    |  |
| T,                | Maximum Lead Temperature for Soldering                                  | 300                      | °C    |  |
| T <sub>SOLD</sub> | 1.6 mm (0.062 in.) from Case for 10                                     | 260                      | °C    |  |
| V <sub>ISOL</sub> | 50/60 Hz, 1 minute  | 2500                     | V~    |  |
| F <sub>c</sub>    | Mounting Force  | 20120/4.527              | N/lb. |  |
| Weight            |   | 5                        | g     |  |

#### **Characteristic Values Symbol Test Conditions** (T<sub>1</sub> = 25°C, Unless Otherwise Specified) Min. Typ. Max. $I_{\rm C} = 1 {\rm mA}, V_{\rm CE} = V_{\rm GE}$ V<sub>GE(th)</sub> 3.0 5.0 $V_{CE} = V_{CES}, V_{GE} = 0V$ 25 µA I<sub>CES</sub> Note 1, T<sub>1</sub> = 125°C 1.5 mA

## $V_{CE} = 0V, V_{GE} = \pm 20V$ GES ±100 nA $I_{\rm C} = 55A, V_{\rm GE} = 15V, \text{ Note 2}$ $\mathbf{V}_{_{\text{CE(sat)}}}$ 2.35 2.20 T<sub>1</sub> = 125°C

#### **Features**

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V~ Electrical Isolation
- Anti-Parallel Ultra Fast Diode
- Optimized for Low Conduction Losses

#### **Advantages**

- High Power Density
- Low Gate Drive Requirement

### **Applications**

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- Inrush Current Protection Circuits



| <b>Symbol</b> (T. = 25°0 | Symbol Test Conditions Characteristic Value (T <sub>.1</sub> = 25°C, Unless Otherwise Specified) Min.   Typ.   Ma |      |           |
|--------------------------|---|------|-----------|
| $g_{fs}$                 | $I_{\rm c} = 55$ A, $V_{\rm ce} = 10$ V, Note 2   | 45   | S         |
| C <sub>ies</sub>         | )   | 4340 | pF        |
| C <sub>oes</sub>         | $V_{CE} = 25V, V_{GE} = 0V, f = 1 MHz$  | 300  | pF        |
| C <sub>res</sub>         | )   | 115  | pF        |
| $Q_{g(on)}$              |   | 185  | nC        |
| $\mathbf{Q}_{ge}$        |   | 25   | nC        |
| Q <sub>gc</sub>          | )   | 75   | nC        |
| t <sub>d(on)</sub>       | )   | 23   | ns        |
| t <sub>ri</sub>          | Inductive load, T <sub>J</sub> = 25°C   | 42   | ns        |
| E <sub>on</sub>          | $I_{\rm C} = 55A, V_{\rm GE} = 15V$   | 5.1  | mJ        |
| $\mathbf{t}_{d(off)}$    | $V_{CE} = 0.8 \cdot V_{CES}, R_{G} = 3\Omega$   | 365  | ns        |
| t <sub>fi</sub>          | Note 3  | 282  | ns        |
| E <sub>off</sub>         | J   | 13.3 | mJ        |
| t <sub>d(on)</sub>       | <b>)</b>  | 24   | ns        |
| t <sub>ri</sub>          | Inductive load, T <sub>J</sub> = 125°C  | 46   | ns        |
| E <sub>on</sub>          | $I_{\rm C} = 55A, V_{\rm GE} = 15V$   | 9.5  | mJ        |
| $\mathbf{t}_{d(off)}$    | $V_{CE} = 0.8 \cdot V_{CES}, R_{G} = 3\Omega$   | 618  | ns        |
| t <sub>fi</sub>          | Note 3  | 635  | ns        |
| E <sub>off</sub>         | J   | 29.0 | mJ        |
| R <sub>thJC</sub>        |   |      | 0.62 °C/W |
| R <sub>thCK</sub>        |   | 0.15 | °C/W      |

#### **Reverse Diode (FRED)**

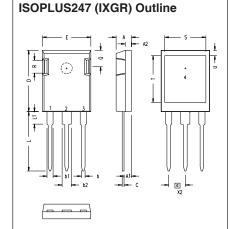
| SymbolTest ConditionsChara $(T_J = 25^{\circ}C, Unless Otherwise Specified)$ Min. |   |  | acteristic<br>Typ. | Values<br>Max. |         |     |
|---|---|--|--------------------|----------------|---------|-----|
| V <sub>F</sub>  |   | $I_F = 60A, V_{GE} = 0V, \text{ Note 2}$ $T_J = 150^{\circ}\text{C}$ |                    | 1.85<br>1.90   | 2.5     | V   |
| t <sub>rr</sub>   | } | $I_{\rm F} = 60A, \ V_{\rm GE} = 0V,$                                |                    | 200            |         | ns  |
| I <sub>RM</sub>   | J | $-di_{F}/dt = 350A/\mu s, V_{R} = 600V, T_{J} = 100^{\circ}C$        |                    | 24.6           |         | Α   |
| R <sub>thJC</sub>   |   |  |                    |                | 0.42 °C | C/W |

#### Notes:

- 1. Part must be heatsunk for high-temp Ices measurement.
- 2. Pulse test,  $t \le 300\mu s$ , duty cycle,  $d \le 2\%$ .
- 3. Switching times & energy losses may increase for higher  $V_{CE}(Clamp)$ ,  $T_{J}$  or  $R_{G}$ .

#### ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.



| SYM    | INCHE 2  |      | MILLIMETERS ] |       |  |
|--------|----------|------|---------------|-------|--|
| 2114   | MIN      | MAX  | MIN           | MAX   |  |
| Α      | .190     | .205 | 4.83          | 5.21  |  |
| A1     | .090     | .100 | 2.29          | 2.54  |  |
| A2     | .075     | .085 | 1.91          | 2.16  |  |
| b      | .045     | .055 | 1.14          | 1.40  |  |
| b1     | .075     | .084 | 1.91          | 2.13  |  |
| b2     | .115     | .123 | 2.92          | 3.12  |  |
| С      | .024     | .031 | 0.61          | 0.80  |  |
| D<br>E | .819     | .840 | 20.80         | 21.34 |  |
| E      | .620     | .635 | 15.75         | 16.13 |  |
| е      | .215 BSC |      | 5.45 BSC      |       |  |
| L      | .780     | .800 | 19.81         | 20.32 |  |
| L1     | .150     | .170 | 3.81          | 4.32  |  |
| Q      | .220     | .244 | 5.59          | 6.20  |  |
| R<br>S | .170     | .190 | 4.32          | 4.83  |  |
| S      | .520     | .540 | 13.21         | 13.72 |  |
| Т      | .620     | .640 | 15.75         | 16.26 |  |
| U      | .065     | .080 | 1.65          | 2.03  |  |

except screw hole.

1 - GATE 2 - DRAIN (COLLECTOR) 3 - SOURCE (EMITTER)

4 - NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD

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